

✓ Targets & Evaporation Materials



Copper

robeko manufactures planar and cylindrical sputtering targets for application in electronics and display production. We provide cylindrical monolithic targets of industrial standard size. Thus we guarantee maximum material density, small grain size and maximum power density combined with good recyclability. The raw material is always on stock.

Target size - PLANAR

- ✓ Thickness up to 25 mm
- Diameter (max) = 400 mm
- Target length (max) = 3000 mm

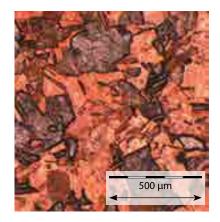


Target size - ROTATABLE

- Inner diameter = 125 mm
- Outer diameter (max) = 163 mm
- Target length (max) = 2800 mm

Applications

- Touch panels
- ✓ TFT LCD
- EMV metallization



Specifications						
Density (%)	Purity (%)	Electrical resistance (μΩ·cm)	Thermal conductivity (W/mK)	Grain size		
> 99.9 (8.96 g/cm ³)	> 99.99 (4N)	1.69	408	180 μm acc. ASTM		

Typical analysis						
Cu	0	Bi	Pb	Others		
> 99.99 %	0.0002 %	0.0001 %	0.0004 %	0.004 %		